



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20070	REV: A	SUN REV: Not In VersionControl
	TID #: PMP20070		
PLOT NAME = Top Assembly Drawing	GENERATED : 3/4/2016	6:00:59 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20070	REV: A	SUN REV: Not In VersionControl
	TID #: PMP20070		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 3/4/2016 6:01:00 PM		TEXAS INSTRUMENTS

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